

Applicant : Ken TAKANO, *et al.*  
Serial No. : 10/795,978

#### IN THE SPECIFICATION

Please amend the paragraph beginning on page 8, line 22, as follows:

The component mounting apparatus configured as shown above is provided with a data section 9 that previously internally stores information on the height and mounting positions of components to be mounted, and a control section 7, which is a computer that directs the movements of ~~moves~~ the positions of the suction nozzle 5, mounting head 6, and printed circuit board 3 based upon the data supplied from the data section 9.

*Approved  
11/21/06  
cjm*  
Please amend the paragraph beginning on page 13, line 12, as follows:

The component mounting apparatus 101 according to this embodiment as shown in FIG. 6 comprises: a board transport apparatus 103 that carries in and out of the printed circuit board; a board operating apparatus 140 that can be connected to the board transport apparatus 103 and holds and moves the printed circuit board 3 in X and Y directions during a component mounting operation; reel-type electronic component supply apparatuses 104-1, 104-2 and 105 or a tray-type electronic component supply apparatus 106 accommodating electronic components 1 to be mounted on the ~~printing~~ printed circuit board 3; a mounting head 107 having nozzles 108 for holding electronic components from these electronic component supply apparatuses, for example, by suction operation, and for mounting the components being held by the nozzles at the mounting positions on the printed circuit board 3; the XY robot 115 for moving the mounting head 107 in X and Y directions; recognition apparatuses 102 and 121 for photographing and measuring the holding posture of the electronic components held by the mounting head 107; and a control apparatus 130, which is a computer for controlling movements of at least the XY robot

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115 and the board operating apparatus 140 and performing recognition processing of images supplied from the recognition apparatuses 120 and 121, thereby to correct a different between the above measured holding posture and the mounting posture of the corresponding component on the printed circuit board.